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"Our mission is to empower customer success by being the trusted partner in delivering quality products and innovative solutions for leading electronic manufacturers."

Stenlech
Innovative Problem Solvers

The leading Multi-national SMT Printing Solutions Company



Consistency, reliability and ease of doing business.

In the SMT industry, precise stencils and tooling are essential. These components require meticulous design and prompt delivery, with no room for compromise on quality, speed, or reliability. Any issues or delays can lead to significant costs in an environment where timing is crucial and faults are costly. StenTech excels in offering unmatched quality, specialized products, and reliability.

Having a dependable local supplier is invaluable when issues arise. Experienced engineers ensure flawless designs, and we provide industry-best stencils, tooling and parts and swift delivery times to keep production on schedule and drive your business forward.

StenTech is your dedicated partner for success, Our consistent service enables the uptime reliability of our customers

We always strive to meet your mission critical deadlines without risking quality and trust.

#### Our Team

With a team of over 30 CAD designers, we're here to creatively solve your problems. We're all about precision engineering that's backed by extensive production experience, cutting-edge technology, top-notch sales support and fast turnaround times making it easy to do business together and ensuring peace of mind and reliability for all our customers.

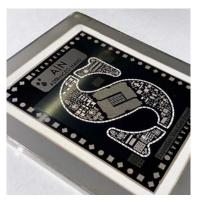
- Largest solutions provider in the industry
- 1-stop shop for all your assembly needs
- 20+ locations for local service
- Fastest turnaround times
- Widest range of products
- Highly skilled multi-disciplinary team
- Unparalleled customer service
- 25 years of excellence

StenTech sets the industry standard for precision, reliability, and speed in SMT printing solutions, delivering unparalleled quality and support to ensure the success of your business.



# **Stencils**

StenTech SMT stencils are the gold standard in the industry, renowned for their precision engineering, unmatched reliability, and our ability to rapidly deliver flawless laser cut and electroform stencils even with the most challenging designs.



# **Tooling**

Our customized advanced tooling and wave solder pallet solutions are uniquely tailored to your specifications and engineered to streamline production processes, enhance quality control, and optimize operational efficiency.



# **Parts**

We specialize in laser-cut and chemically etched precision metal parts. From prototypes to full production, we offer quick quotes, low tooling costs, and fast turnaround.















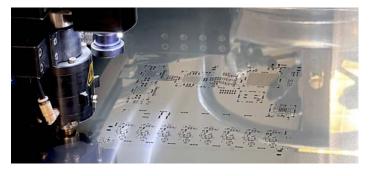
**Laser Stencils** 

**Step Stencils** 

**Materials** 

**SMT Emulsion** Screen

Re-Work Mini **Stencils** 

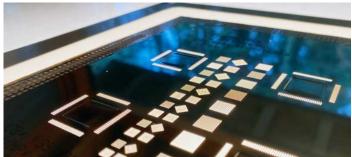




- Positional accuracy of =/- 2 um,
- Dimensional accuracy of +/- 2 um
- Available thickness: 2 mil to 12 mil standards, other thickness is available upon request.
- Available frame size: Standard frame size from 5x5 to 29x71 inch.
- Custom frames are available with limited capabilities.
- Contact your Sales rep or CAD engineers for more information.

StenTech also produces High Definition Print Stencils (HDP) that are manufactured with high tension mesh designed to address the **Chemically Etched SMT Step Stencils:** challenges posed by smaller components. With improved snap-off from board to stencil during the print process, we ensure an exceptional paste deposit on the board.





#### Laser-Welded SMT Step Stencils:

- **Process:** This is an additive process in which a laser is used to achieve the desired metal thickness. Stencils are created with high accuracy and tighter tolerance. Fine grain and phd SS are the common materials for this process
- Features: No surface roughness on the metal, high precision, good squeegee elevation to the step area
- Advantages: Faster turn time, tighter tolerance on the thickness since we are using the same standard material from the vendor
- Considerations: Limitation on the step pocket/area and thickness. Contact our CAD engineers for more information.

- **Process:** This is a subtractive process in which the stencils are created by chemically etching the metal sheets.
- Features: They offer high precision and fine detail on step
- Advantages: etched area could be very large or small. Popular for relief etch stencils for gasketing the board with the stencils and many pockets on a stencil
- Considerations: Thicker the metal, higher the tolerance on the step area. Contact our CAD engineers for more information.

#### Milled SMT Step Stencils:

- **Process:** This is a subtractive process in which the stencils are created by milling away material from a metal sheet,
- Features: Low surface roughness results in better paste
- Advantages: Can be used for thicker stencils with high accuracy and tolerances
- Considerations: Higher cost compared to chemically etched Laser Welded step stencils. Contact our CAD engineers for more information





(PHD is the name of this product, not an acronym)

- Grain size is 5-7 microns
- PHD base material is 304 with proprietary rolling method
- This method reduces the relief tension of the material
- The relief tension eliminates the canning/potato chip effect on BGA's or highly populated boards
- The small grain size creates a smoother aperture wall when cutting and increases paste deposit
- Material thickness tolerance plus/minus 2% material thickness

#### FG

FG stands for Fine Grain

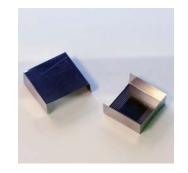
- Grain size is 1-2 microns
- FG base material is 301 with proprietary rolling method
- This method reduces the relief tension of the material
- The relief tension eliminates the canning/potato chip effect on BGA's or highly populated boards
- The small grain size creates a smoother aperture wall when cutting and increases paste deposit.
- Ideal for Ultra fine pitch components with lower AR
- Material thickness tolerance plus/minus 2% material thickness Ideal for stencils with miniature apertures

## **Nickel Blanks**

- Grain size Nano microns
- Grown blanks using Electroform process
- Control thicknesses allows for increments of .1 mil therefore sheet thicknesses can be 3, 3.1, 3.2 up-to 7 mil
- Durable
- Material thickness tolerance plus/minus 5% material thickness



StenTech produces SMT Emulsion StenTech's BGA Re-Work Mini Screens known for their versatility in printing. This process involves for precise solder paste application stretching mesh onto a frame, during BGA rework on PCBs. These applying emulsion, and imaging stencils match the footprint and the mesh for printing. Emulsion aperture sizes of the original screens are crucial in industries like production stencil for accuracy. automotive and microelectronics They come with holders and that require precise deposits and squeegee blades for easy solder line widths. StenTech ensures its paste application. StenTech can screens meet these specifications. Emulsion screens are widely used components using Gerber data or in various industries such as mechanical drawings. The mini display, advertising, aerospace, microelectronics, textiles, ceramics, circuit board production, and glass or for manual printing. They are printing. StenTech offers a range of stable, flat, and designed not to mesh options including polyester, stainless steel, nickel mesh, and Side reinforcements prevent nickel-polyester combinations, each with unique weaves and thread thicknesses.



Stencils are small stencils made create rework stencils for various stencils are designed for use with dedicated BGA rework systems contaminate surrounding areas. shifting, and front ramps prevent paste spillage. Custom squeegee blades are included for each mini stencil, and flat plates or mounted flat plates are available for use when there is enough space around the components on the board.

For our full range of ELECTROFORM Stencils please see StenTech's PhotoStencil Specialized Products Division section.







# COATING

## StenTech Advanced Nano™

StenTech's award winning Advanced Nano is an exceptional coating that revolutionizes stencil technology. Unlike traditional stencils, this highly unique coating is applied to the bottom side of the stencil and inside the apertures, leaving the squeegee side uncoated. This advanced coating grants the stencil remarkable anti-adhesion properties, preventing solder / flux from sticking to it. Utilizing a specialized 1-2 um hardened nano coating, Stentech's Advanced Nano stencil boasts a permanent hydrophobic layer that repels solder flux.

Consequently, this innovative feature facilitates enhanced paste transfer during printing processes, leading to improved efficiency and precision in electronic manufacturing. Most of all it allows for **SAME DAY DELIVERY of your stencils** where possible.

Applying AIN to your solder stencil can increase paste release as much as 25%

# **Quickest lead time of a coated stencil**

(A|N is fully cured for use 10 min after coating)

# **Allows for same day SHIPMENT!**

- Coating is cured and ready to use/clean in 10mins
- Higher volume of paste release
- More uniform shape on solder deposits
- Higher transfer efficiency and print yields
- Reduced underside wiping
- Reduced surface energy of the paste contact area
- Better contour definition and lower failure.
- AlN thickness variance is +/- 1 micron across any stencil
- Greater yields on low-area-ratio / miniaturized applications

# **TECHNOLOGY**

## StenTech BluPrint™ PVD Stencils.

StenTech BluPrint™ eliminates the need for frequent replacements and ensures a longer lifespan for the stencil, ultimately reducing maintenance and replacement costs associated with traditional coatings while dramatically enhancing overall performance.

We are proud to present our latest innovation in stencil coating technology - the all new StenTech BluPrint™ PVD (Physical Vapor Deposited) Surface Treatment. Engineered to elevate the Surface Mount Technology (SMT) processes, this advanced coating offers a comprehensive set of benefits that collectively contribute to improved stencil performance, longevity, and the overall quality of the SMT assembly process streamlining production.

# **WINNER:** 2024 CIRCUITS ASSEMBLY NPI AWARD

The continuous drive to reduce component sizes and circuit boards poses a challenge for solder paste printing with laser-cut stainless-steel stencils. Laser technology advancements align with coating finish improvements for these stencils. StenTech's BluPrint™ PVD is meticulously designed to be the top choice in North America for meeting the evolving requirements of the semiconductor and EMS industry.

# StenTech.com/BluPrint















StenTech.com/advancednano



# **TOOLING & PALLETS**

**Wave Solder Pallets** 

**SMT Carriers** 

**Pressfit Fixtures** 

**Vacuum Print Support Fixtures** 

Routing (De-Panelizer) Fixture

# **Full Product Range** & Code System



StenTech offers cutting-edge capabilities in machining and designed to provide precise designed to provide support for are crucial for supporting circuit drilling composite materials, allowing for the creation of customengineered wave solder pallets tailored to each client's needs. These pallets are designed to enhance overall process efficiency, reducing setup time and enabling the wave soldering of complex, doublesided circuit board assemblies. Additionally, they eliminate the need for expensive and labor-intensive masking, while also shielding heat-

StenTech's wave solder pallets enable the simultaneous processing of multiple boards, reducing issues like bridging and skipping. This not but also enhances automated assembly processes, making them Standardizing the process with connector assembly. an ideal choice for improving wave these carriers ensures consistent soldering operations.

sensitive components.



StenTech's SMT Carriers are StenTech's Press Fit Fixtures are StenTech's Vacuum Support Fixtures durability and reliability. SMT customer's specifications. carriers for PCBs provide enhanced located near the board edge.

benefits, including a reduction in setup time and the elimination of unnecessary handling of PCB boards by operators. They also results and minimizes soldering defects, making them an essential tool for improving surface mount assembly operations.



alignment and secure holding circuit boards during the insertion of of circuit boards throughout the press fit connectors, which requires assembly process. These carriers significant force. These fixtures are are constructed from high- made from materials such as ESD fixtures prevent warping, sagging, temperature semi-conductive composite, G10, aluminum 6061, composite materials, ensuring or stainless steel, based on the support for double-sided boards.

only increases production rates the need for expensive hand boards, making them a versatile for SMT success. masking, and reduce labor costs. and efficient solution for press fit



boards during SMT assembly, especially with increasingly complex board designs. These and bending, ensuring proper

Using Vacuum Plates offers support to ensure optimal printing Using Press Fit Fixtures offers several benefits, including easy quality, particularly for connectors several advantages, including setup, consistent board support complete support for press fit for paste deposits, and reduced components and a reduction in the rework, leading to cost savings. The use of SMT Carriers offers several risk of damage during the insertion Dedicated tooling like Vacuum process. They also help reduce costs Plates is an industry standard and setup time in manufacturing for fast and repeatable setup, processes. Additionally, universal maintaining process stability, and fixtures can be quickly modified reducing variation and defects in minimize board warping, eliminate to accommodate a variety of the screen-print process, crucial

> Maintaining a flat and stable Z plane of the board is crucial, as variations can cause difficult-to-troubleshoot defects. Dedicated screen-print tooling reduces variation and defects, ensuring stable setup and process consistency in SMT assembly.



StenTech routing (de-panelizer) fixtures are a specialized tool used in the PCB (Printed Circuit Board) assembly process. It is designed to securely hold a panel of PCBs while a routing machine cuts the individual boards from the panel. The fixture ensures precise alignment and support for the panel during the routing process, preventing damage to the PCBs and ensuring clean, accurate cuts. Routing fixtures are essential for efficient and reliable PCB assembly, especially in highvolume production environments.











RWF	Rework Fixture
UNF	Underfill Fixture
ADP	Adjustable Pallet (Universal)
SKY	Skybar = CANOPY
HDB	Hold Down Bar
MTR	Material
TPL	Trim Plate
MOD	Modification on a Stentech part or job
СРМ	Custom Part Modification
EDT	Engineering Design Time
CCF	Conformal Coating Fixture
WSB	Wash Basket
WSF	Wash Fixture
5DX	5DX Fixture
XRY	X-RAY FIXTURE
JDC	JEDEC FIXTURE
AOI	AOI Fixture
AXI	AXI FIXTURE
ВРВ	Blank PCB Board
RBF	Reballing Fixture
CUF	Custom Fixture, Description needed
CUP	Custom Part, Description needed
FPF	Flying Probe Fixture
GNG	Go/No Go
HSF	Hand Solder Fixture
PFF	Pressfit Fixture
PFI	Pressfit Insert (Cage support)
PFD	Pressfit Die
SMT	SMT Fixture (Printing, P&P, Reflow)
DRF	Depaneling Router Fixture
SSF	Selective Soldering Fixture
PSP	Print Support Plate
WSP	Wave Solder Pallet
ACC	Accessories





chemically etched precision parts produced to the exact specs that your project demands. From prototype to full production, with expert manufacturing, engineering and support teams, we provide rapid quoting, low tooling costs and fast turnaround times including quick design changes. Our facilities are equipped with the most advanced state-of-the-art technology that enables us to deliver exceptional, affordable quality parts with trusted repeatability.

#### **Laser Cut Parts**

StenTech specializes in laser-cut parts, providing solutions for all applications. We ensure tight tolerances of ±0.001" and even tighter, with cutting tolerances starting from ±0.15 mm. Our capabilities include cutting dimensions up to 1500 x 3000 mm and cutting thicknesses ranging from 0.3 mm to 8 mm.

## **Chemically Etched Parts**

Chemical etching is a process that shapes metal sheets by using etchants. At StenTech, we use this method to create precise components from various metals. It's a cost-effective way to profile and shape parts for precision applications, providing accuracy, speed, and unique properties. Unlike stamping and CNC machining, which can compromise metal integrity, chemical etching preserves it.

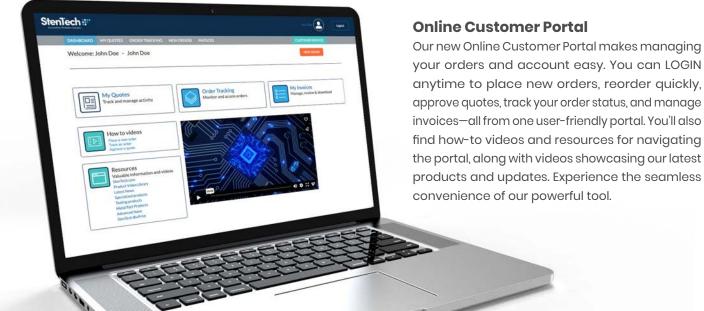
- Wide variety of metals & finishes
- CAD / CAM in-house
- Rapid prototyping
- Low tooling costs
- Precision engineered
- Large volumes
- Tight tolerances
- Tabbed in or individual pieces
- Burr free
- Long production life

Exceptional, affordable quality parts with trusted repeatability.

StenTech.com/Parts



# **SERVICE & SUPPORT**





At StenTech, we pride ourselves on our expertise, speed, and reliability. We always aim to make doing business with us easy and our account managers are always here to help.

**Step One** 

order begins.

for production.

**ORDERS & ACCOUNT SET-UP** 

New customers can request a quote

will assign an account manager and

engineer to review the job details and

proval, an account is set up, and your

swiftly send back a quote. Upon ap-

on StenTech.com by submitting

specifications and files. Our team

**Step Two** 

### **PRODUCTION**

Your order is quickly put into production.
We manufacture prototypes to full finished production pieces, and the turnaround time depends on the order's complexity. Each job undergoes rigorous inspection before shipping.

We understand the importance of time, so we prioritize fast quote turnaround and order processing
 We always strive to meet your mission critical deadlines without risking quality and trust.

StepThree

## **FULFILLMENT**

We are committed to on-time delivery and ensure timely and accurate delivery of your jobs, consistently striving to provide exceptional service throughout the entire process.

 Your satisfaction and peace of mind are our top priorities.



With more than 25 years of industry experience, we are recognized as the foremost provider of advanced solutions for complex paste, flux, epoxy, and specialized materials printing requirements.



# We're problem solvers

Photo Stencil's Applications **Engineering Team comprises** world-leading experts in stencil printing. Whether you're dealing with challenges like poor paste release or tiny aperture requirements down to micron wafer levels, our team is here to help. We see ourselves as an extension of your R&D team, ready to solve your printing challenges.

Photo Stencil's diverse product technologies require our inspection teams to have the expertise necessary to ensure your products meet the highest standards of quality and functionality.

# **Equipped to** deliver

Our recently updated 35,000 sq. ft. factory in Golden, Colorado, houses state-of-the-art chemical plating production lines, R&D labs, clean rooms and precision fabrication equipment with end-to-end technology, including LED direct imaging (LDI) and AOI inspection, Advanced Nano coating and the revolutionary new StenTech BluPrint™ CVD (Chemical Vapor Deposited) Surface Treatment.

In addition to a comprehensive selection of SMT Stencils, we manufacture specialized tooling and custom wave solder pallet solutions that are meticulously crafted to match your specific requirements.

# Teamwork & timing is everything

When issues arise, having a dependable supplier who can promptly address them is invaluable. It requires an experienced team with technical expertise to ensure flawless designs from the start, solid production, and effective communication, all leading to a guarantee of 100% reliability.

Delivery times typically range from two to fourteen days depending upon the complexity of the job and the volumes required.

Our goal is to offer customers unmatched service and technical expertise, providing great value, exceptional quality, and on-time delivery.

# The foremost authority

in electroform stencils.

Photo Stencil, is the leading provider of the most complex electroforming precision paste, flux, ball-drop, wafer bump and 3d stencils and screens in North America.

Photo Stencil, StenTech's specialized products division, is a global leader in electroform stencil technology for the semiconductor and EMS industry. We offer cutting-edge products with micron-level precision and a wide range of specialized solutions, techniques, and materials not available elsewhere in North America.

- Exclusive and unique specialized solutions
- Expertise in electroform stencil technology
- Highly trained CAD engineers
- Prototypes to high-volume manufacturing
- Advanced metrology capabilities
- Revolutionary StenTech BluPrint™ VDC
- Unrivaled customer service
- · Unmatched quality and reliability



StenTech.com/Photostencil



# **SPECIALTY SOLUTIONS**

AMTX™ Standard **Electroformed Stencils** 

# **AccuScreen Electroform Mesh Stencils**

# NiEX™ **Hard Nickel Electroformed Stencils**

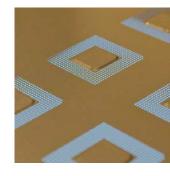
# **Step Stencils** Electroformed, Laser **Cut & Chemical**

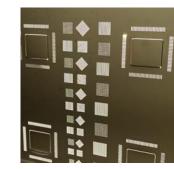
# 3-D **Electroformed Stencils**

# **Wafer Bump Stencils**

## **Wafer Ball Drop Stencils**



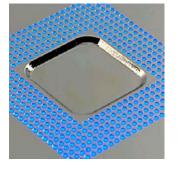


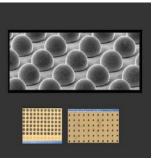


NiCut™

**Electroformed Stencils** 

w/laser apertures





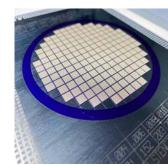


Photo Stencil holds the exclusive AccuScreen provides a high NiEX™ electroformed stencils use NiCut™ stencils are our standard manufacturing rights for the performance metal mask/screen the same proprietary process as our Electroform (AMTX) Nickel patented AMTX electroformed fabricated using an additive market leading AMTX™ stencils. The Stencils with Laser Cut Apertures. stencil the meticulous process for crafting metal stencils and parts, printed by mesh of apertures to Hardness (HK) than our standard stencil, followed by a secondary accomplished by depositing atoms control print volume. Primarily used AMTX product for those very thin process utilizing Photo Stencil's one by one. This method yields an for printing on flexible electronics, less than .003 applications such own proprietary technology, which exceptionally precise duplicate to print varieties of pastes and as wafer bumping or flux printing, further extends the capabilities. from an initial mandrel or master inks. Various mesh sizes and wire Available in 1 to 3 mil thicknesses.. These stencils utilize our electroform surface. AMTX Electroforming thicknesses are available with provides exceptional repeatability and capacity to handle intricate thickness and screen variation designs. The nickel growth, atom are also possible. by atom, around photo resist pillars during the Electroform Stencil Reservoir Stencils are a special case and resistor networks process results in mirror-like of single thickness 3D electroform aperture walls. These walls excel in facilitating the effortless release of solder paste compared to the walls of laser-cut apertures...

stencil used to print into a recessed pocket of the board. Stencil grown using the electroform process followed by - laser cutting of apertures (optional).

density and mixed components, NiEX™ is ideal for fine pitch components including BGAs, QFNs

process (Ni). Each large area is NiEX™ stencil has a higher Knoop Beginning life as an electroform blank foil material to obtain the the standard sizes. Additional Ideal for applications with high smoothest cut from our fiber optic Photo Stencil's step stencils offer Our 3-D Electroform stencils are Wafer bumping stencils are significant flexibility in achieving ideal for printing on substrate electroform stencils used to obtain the proper solder paste height surfaces that have protrusions bumps on wafer pads. The stencil and solder paste volume for the rising above the print surface. An usually has from 25,000 apertures overall paste printing process. example of this type protrusion up to 500,000 apertures. Photo Stencil is pioneer in the field might be a flip-chip device already of Step Stencil technology with all mounted on the PCB prior to solder Photo Stencil produces two different processes contained in house for paste printing. This is a single sets of stencil to achieve this (a) the most comprehensive service thickness electroform stencil, with Paste Print stencils: A print process available in the industry.

relief areas not to damage the where solder paste is printed on protruded sections on the board die pad on the wafer, the wafer is or unit.

A single thickness Electroform (bumps) on the wafer die Stencil is formed with a raised relief pocket positioned over the protrusion. A squeegee blade with a 25micron slit is ideal for allowing the squeegee blade to raise up over the raised pocket but still be able to print in front of and behind the raised pocket.

then re-flowed, melting the solder paste to form truncated spheres Stand off on wafer Ball drop stencil

This is the second stencil from the set of Flux and ball-drop process used in wafer bumping. Flux is printed on to wafer pads using 1st stencil followed by using a wafer ball drop stencil to drop solder balls directly onto the connection pads of a wafer. Since flux is printed onto the wafer pads before the ball is dropped, it has optional relief or standoffs placed on contact side.

can be obtained by:

1. Laminating a mask (photo resist) on the wafer side of the stencil to keep the stencil from contacting the flux.

2. E-form Nickel rib layer is grown on wafer side.

- Smooth aperture walls promote
- Lower area ratios of the order of 0.43. • Improved under screen cleaning
- (USC) performance and reduced cleaning frequency.
- Excellent tensile strength and hardness:
- Increases stencil life.

- Tailor different mesh patterns can be used, as per paste/flux properties. Eg: hexagonal, oval, rectangles, sauares, circles
- Mesh shape can be adjusted to material flow properties and viscosity
- and higher printing yields.
- · Less pattern distortion since flat electroformed mesh does not stretch like screen wire mesh

- · Quick turn for large aperture count.
- excellent paste transfer.
- Lower area ratios of the order of 0.43.
- Improved under screen cleaning (USC) performance and reduced cleaning frequency.
- Excellent tensile strength and
- Increases stencil life.

- Ideal for applications with high
- NiCut is ideal for fine pitch com-

- · Available as 'step up' and 'step down' squeegee side, 'step up' PCB side or on both sides.
- Ideal for providing bar code relief and thus maintaining the maximum gasket.
- Matched Slit squeegee blades allow for flexure over the raised pocket
- Multi-thickness steps available.

- · Successful solder paste or flux printing
- Simplified process for multi level printing.
- Single stencil requirement multi function design.
- · Higher assembly yields from successful solder paste printing.
- · Useful for bumping of wafers of various sizes and bump count and bump size (<200um).
- Typically used when pitch is at least more than 2 times the bump diameter. (b) Flux print +Ball Drop Stencils: Set of two stencils.
- · Ball drop stencils are used for different wafer sizes, sphere size and
- Easy to use, regular solder paste printer can be used for manual ball drop.
- Ball drop process is also preferred when the wafer pad is larger or pitch is tighter to use paste printing application.
- · Used instead of wafer bumping using paste printing

- Quick turn for large aperture count. excellent paste transfer.

  - · Greater print deposit uniformity

- Smooth aperture walls promote density and mixed components.
  - ponents including BGAs, QFNs and resistor networks.
  - · This stencil is surpassed only by our electroformed stencils.

# **PRODUCTION**

**CAD ENGINEERING** 

## **IMAGING**

# **DEVELOPING**

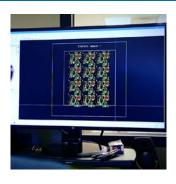
# **CHEMISTRY LABORATORY**

## **CHEMICAL PLATING**

# LASER CUTTING

# ADVANCED NANO CHEMICAL VAPOR COATING

# COATING













Our team of CAD design experts We've recently integrated a cutting- We have recently upgraded to Our laboratory technicians have by filtering the Gerber file's D-codes. of 3-4 microns. It ensures that the proposed design achieves the necessary area ratio (AR) for a successful paste deposit.

provide customers with a edge Niva Tech LED Imager, which state-of-the-art IPS Developer/ expertise in regularly testing all comprehensive design service. has replaced traditional analog Dryer equipment, which has the chemical solutions within This service includes using our film plotting. This advancement been specially customized for the production flow, verifying the exclusive front-end software tool has significantly improved the Photo Stencil. This advanced accuracy of the chemicals in StenCAD, which automatically imaging process, aligning the system significantly streamlines the processing tanks on a daily examines each assembly's design output with a remarkable precision and enhances the development basis. This practice stabilizes the quality, and faster processing.

process, thanks to its vertical electrochemical reaction, leading track-fed configuration, resulting to the creation of electroform in improved consistency, superior stencils that exhibit exceptional precision and intricate features.

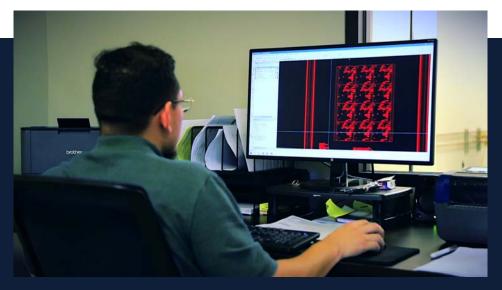
Our chemical plating production Our facility is equipped with Our exclusive Advanced Nano StenTech BluPrint™CVD (Chemical center has undergone a redesign numerous cutting-edge LPKF 6080 aimed at optimizing production High-speed laser systems that adhesion properties, preventing Treatment for Stencils stands as processes and achieving notable feature ultra-light carbon fiber axis solder flux / paste from sticking a North American exclusive, offering advancements in stencil thickness construction. Additionally, we utilize to it. Utilizing a specialized 1-2 um the market's most premium stencil and quality control. This facility the lightning-fast Tannlin TII laser, hardened nano coating, Stentech's coating. This revolutionary process boasts the most cutting-edge a highly integrated stencil cutting Advanced Nano stencils boasts a equipment for chemical-etched machine, to provide large-format, stencils, establishing us as the high-volume output, exceptional unmatched leader in capability speed, and consistent precision throughout North America.

stencil production

permanent hydrophobic layer that repels solder flux / paste.

coating grants the stencil top anti- Vapor Deposited) Surface ensures increased durability, enhanced accuracy, superior performance, and a longer stencil lifespan.

# **ENGINEERING & DESIGN**



StenTech also offers you the opportunity to take advantage of our design service, which includes a front-end software tool called StenCAD that automatically checks the design for each individual assembly by filtering each D-code of the Gerber file and validating that the AR achieved by the proposed design delivers a successful paste deposit.



# **QUALITY INSPECTION**

**METROLOGY** 

## **APERTURE SCAN**

# **OUR LOCATIONS**

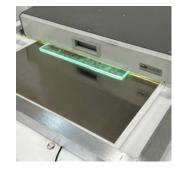
# StenTech.com/Locations



# **VERIFICATION**

## HAND CRAFTED **FINISHING**









to Al inspections of micro defects, our team combines a multitude of advanced inspection, assembly,

provides a range of analytical to ensure precise inspection. options, both destructive and non-destructive.

We have Lupine measurement Our Scan Cad / Automated Our new Micro View non-contact Our production and inspection equipment enabling us to employ Optical Inspection (AOI) equipment and multi-sensor measurement team is exceptionally skilled and high precision metrology. From facilitates automated detection machine is furnished with cutting- knowledgeable, committed to measuring nanometers of thin film, and identification of defects and edge metrology software. It can ensuring that every SMT stencil anomalies. It possesses the ability to measure parts as long as 2.5 meters and tooling device meets perfect precisely record the configuration, and weighing up to 100 kilograms. specifications. Through their compatibility, and operation of The high-resolution digital camera meticulous craftsmanship, they and measurement technologies. all layers, including those with is equipped with programmable guarantee quality, precision, and concealed vias. This technology optical and digital zoom features utmost care in the manufacturing



"Great things in business are never done by one person; they're done by a team of people." - Steve Jobs



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